

NOTES:UNLESS OTHERWISE SPECIFIED

1. Final assembly shall be clean, free of debris and free of sharp edges.
2. Inspection: There shall be no solder balls, solder splash and/or other debris on the PCB and its components.
3. Finished assembly to be RoHS compliant.
4. PCB manufacturing and assembly to be according to data files shown in Gerber file table listed in bare board drawing.
5. Placement of SMT components to be according to IPC-610 standard Class 3.
6. Placement of Through-Hole components to be according to IPC-610 standard Class 2.
7. Workmanship shall be per IPC-J-STD 001 and IPC-A-610 latest revision.
8. Packaging: Final assemblies are to be sealed in separate Electrostatic Dissipative (ESD) bags with appropriate markings.
9. Components more than 6 months old (or the period guaranteed by manufacturer, as long as it does not exceed 18 months) shall not be used without a solderability test performed every 6 months thereafter.
10. A certificate of compliance is to be submitted with each batch according to IPC-2221/22.
11. Testing: End-Of-Line electrical testing to be performed according to specification provided.
All Bare board to be electrical tested.



SILKSCREEN TOP

ENGINEER: Scott Jenney	DRAWN BY: Scott Jenney	BOARD NUMBER: ISLI2UEV1Z Intersil Corporation 1001 MURPHY RANCH RD MILPITAS CA 95035	
RELEASED BY:	DATE DRAWN: April 18, 2016		
UPDATED BY:	DATE RELEASED:		
intersil	DATE UPDATED:	NAS#	HSNR ID: B
	FILENAME Microcontroller Interface Board		SHEET 1 OF 1